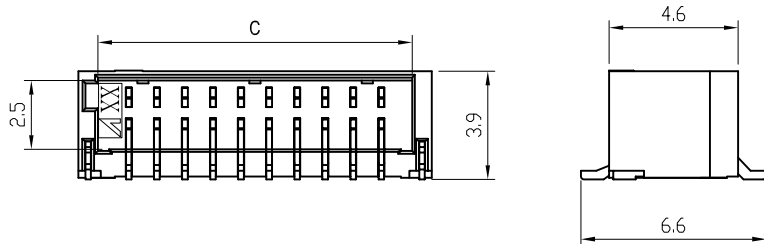
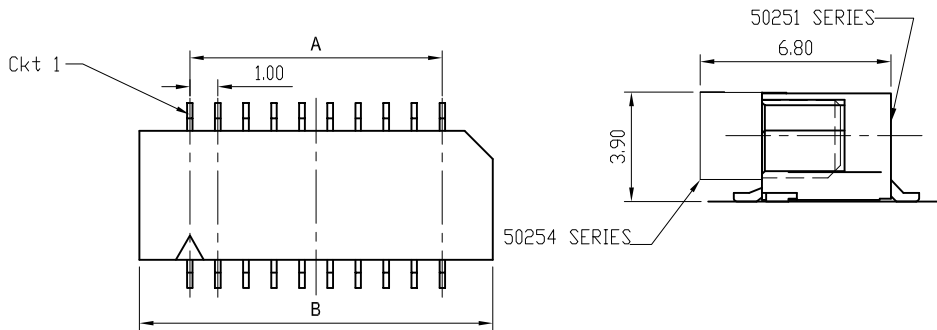


RECOMMENDED PCB LAYOUT



NTOES:

1, MATERIALS:

HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP, UL94V-0.  
CONTACT: COPPER ALLOY.  
FITTING NAIL: COPPER ALLOY.

2, PLATING:

2.1 CONTACT:

UNDERPLATING: 50~100u" NICKEL OVERALL.  
L: TIN-LEAD 120~150u" ALLOVER  
I: GOLD FLASH OVERALL FOR LEAD FREE.  
N: 120~150u" MATT TINKLEAD FREE) OVERALL FOR LEAD FREE.  
C: 15u" GOLD ON CONTACT FOR LEAD FREE  
GOLD FLASH ON SOLDER AREA  
D: 30u" GOLD ON CONTACT FOR LEAD FREE  
GOLD FLASH ON SOLDER AREA

2.2 FITTING NAIL:

UNDERPLATING: 50u" MIN NICKEL OVERALL.  
I: GOLD FLASH OVERALL  
N: 120u" MIN MATT TIN OVERALL.

3, REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4, SPEC. PLS. REFER TO PS-50251-XXXX-XXX

5, PACKAGE PLS. SEE P/N LEGEND

6, PART NUMBER.

P/N LEGEND

50251-XXX X X-XXX

No. of Ckts

Packing

0: Tape & Reel

1: Tube

XXX	Material&Color	PACKING
001	HF Plastic&Black	88242-XXXXX-TRP
002	HF Plastic&Black	88242-XXXXX-U-TRP
S01	HF Plastic&Black	88242-XXXXX-U-TRP
S02	HF Plastic&Natural	

Plating

L: Lead Free (Pure Tin)  
I: G/F over all (lead free)  
N: Matt Tin (Lead Free)  
C: 15u" Gold on contact (Lead Free)  
D: 30u" Gold on contact (Lead Free)

CKTS	DIM A	DIM B	DIM C
6	2	5.6	4.2
8	3	6.6	5.2
10	4	7.6	6.2
12	5	8.6	7.2
14	6	9.6	8.2
16	7	10.6	9.2
18	8	11.6	10.2
20	9	12.6	11.2
22	10	13.6	12.2
24	11	14.6	13.2
26	12	15.6	14.2
28	13	16.6	15.2
30	14	17.6	16.2
32	15	18.6	17.2
34	16	19.6	18.2
36	17	20.6	19.2
38	18	21.6	20.2
40	19	22.6	21.2
42	20	23.6	22.2
44	21	24.6	23.2
46	22	25.6	24.2
48	23	26.6	25.2
50	24	27.6	26.2

PROPOSAL DRAWING

<b>QUALITY SYMBOLS</b> MAJOR Ⓜ CRITICAL Ⓢ <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY SHISONGTAO	DATE 19/04/09		
	CHECKED BY XuZhiYong	DATE 19/04/09		
	APPROVED BY XuZhiYong	DATE 19/04/09	TITLE 1.0mm WTB WAFER R/A D/R SMT TYPE	RFO NO. N/A
	UNITS mm		SIZE A4	DWG NO. 50251-XXXXX-XXX
SCALE 1:1	SHEET NO. 1 OF 1	REV D		